Abstracts

Coax via-A technique to reduce crosstalk and enhance impedance match at vias in high-frequency multilayer packages verified by FDTD and MoM modeling

E.R. Pillai. "Coax via-A technique to reduce crosstalk and enhance impedance match at vias in high-frequency multilayer packages verified by FDTD and MoM modeling." 1997 Transactions on Microwave Theory and Techniques 45.10 (Oct. 1997, Part II [T-MTT] (Special Issue on Interconnects and Packaging)): 1981-1985.

Large-scale crosstalk at vias and poor via electrical performance are major drawbacks in state-of-the-art high-frequency multilayer first- or second-level integrated-circuit/monolithic-microwave integrated-circuit (IC/MMIC) packages. The coax via design modeled in this paper breaks new ground in achieving more than 30-dB ultrawide-band crosstalk reduction and providing an enhanced impedance match.

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